

System specification (1)

Productivity	UPH	Unit/hour	21,000 (Based on dry running)
Application	Wafer Size	inch	Max 8.0 inch
	Slotted Magazine	ea	4 (Loader/Unloader)
	Stacker (Optional)	ea	1 (Loader)
System Reliability	MTBA	hours	2
	MTBF	hours	168
	MTTA	minutes	Max. 3
	MTTR	minutes	Max. 30

System specification (2)

Die Placement Accuracy	um	+/-25.4um @ 3σ XY Placement
Die Rotation Accuracy	°	+/- 1° @ 3σ Die rotation
Minimum applicable die size	mm	0.20 x 0.20
Applicable Lead Frame size	mm	20 ~ 75(Width) 120 ~ 270(Length)
Vision	-	3 CAMERAS (DISPENSING, WAFER, BONDING STAGE)
Dimension	mm	700mm X 1,100mm X 1,500mm (Without LOADER/UNLOADER) 1,400mm X 1,100mm X 1,500mm (With LOADER/UNLOADER)